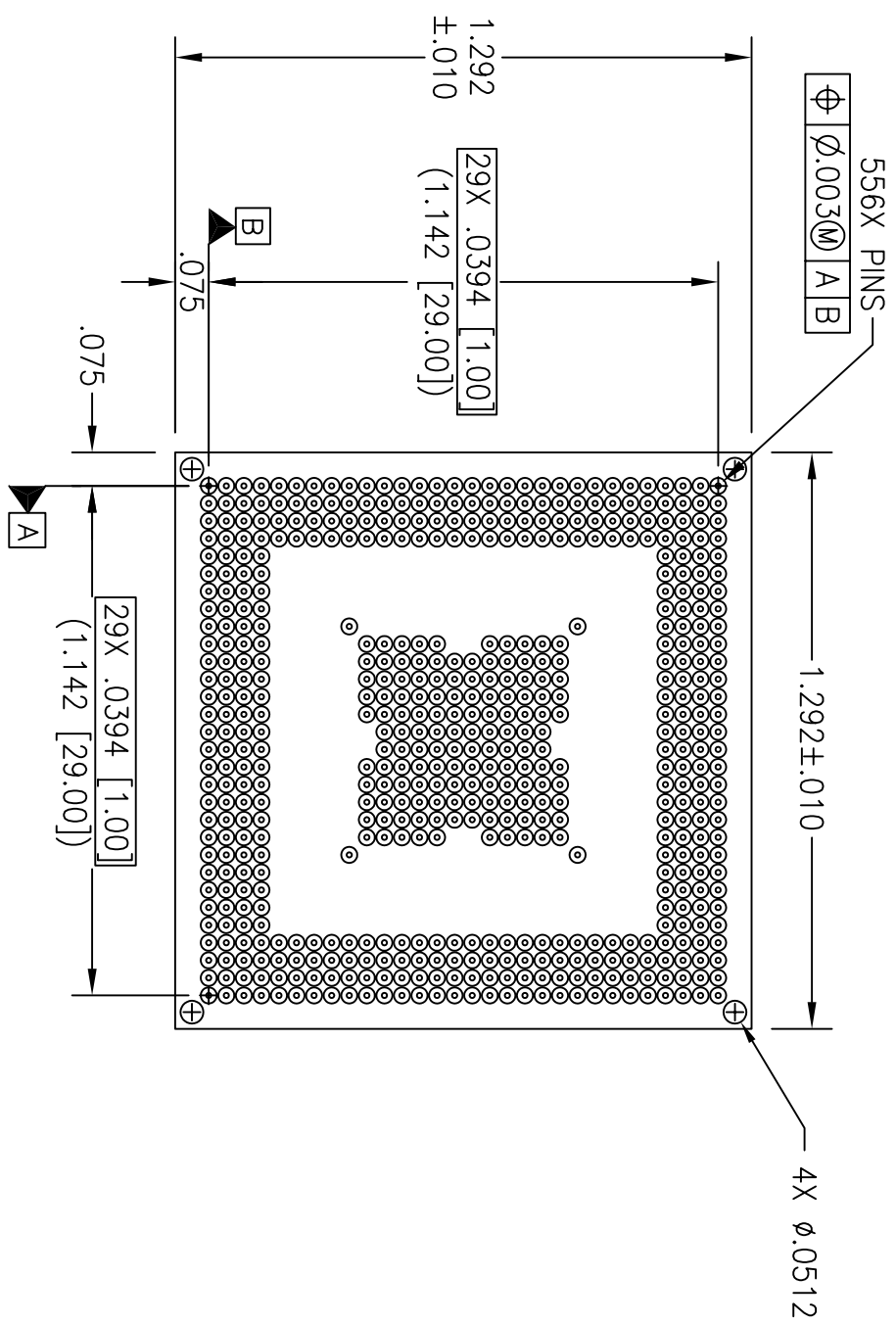
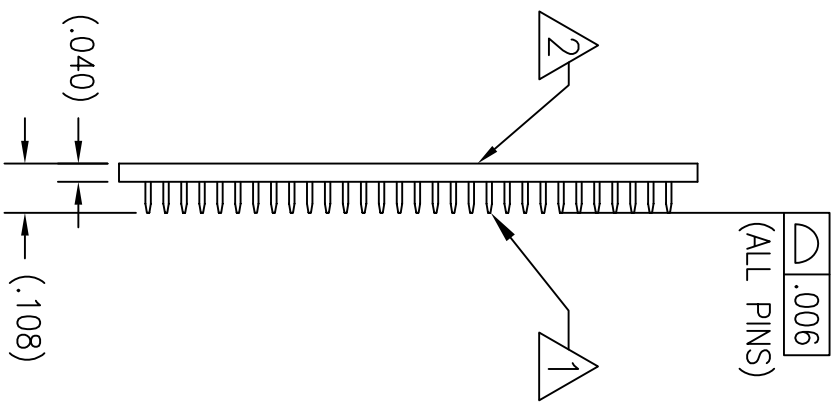


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TOP VIEW



RS VIEW



- NOTES:
- PINS  $\phi$ :0.0117  
MATERIAL: PHOSPHOR BRONZE.  
PLATING: HARD GOLD OVER NICKEL.
  - INSULATOR MATERIAL: FR4.

REV	DESCRIPTION	ECN	DATE	RELEASE
1	SALES RELEASE			

CONTRACT NO.		DRAWN BY		DATE	TITLE	
UNLESS OTHERWISE SPECIFIED:		DESIGNER		DATE	HIL0-BGA PIN BASE	
DIMENSIONS ARE IN INCHES		CHECKER		DATE	30 X 30, 556 PINS	
TOLERANCES:				DATE	1mm PITCH	
ANGLES: $\pm$ 1/64				DATE		
FRACTIONS: 1/32		DATE		DATE	SCALE: N/A	
DECIMALS: 4.010		DATE		DATE	DRAWING NO. HLP-300556-B-10	
.XXX		DATE		DATE	FISHED ASST. HLP-300556-B-10	
.XXXX		DATE		DATE	SHEET 1 OF 1	
		DATE		DATE		

INTERCONNECT SYSTEMS INC.  
708 VIA ALONDRA, CAMARILLO, CA 93012